

N-Channel MOSFET

General Description

The WSR180N06 uses advanced SGT MOSFET to provide excellent R_{DS(ON)}, low gate charge

This device is suitable for use as a Battery protection or in other Switching application.

Features

- 100% UIS + R_g Tested.
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)
- Moisture Sensitivity Level MSL1 (per JEDEC J-STD-020D)

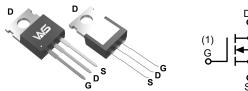
Product Summery

BV _{DSS}	R _{DS(ON)}	I _D
60V	2.4mΩ	150A

Applications

 Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems.

TO-220-3L Pin Configuration





Absolute Maximum Ratings (T_A=25°C, Unless Otherwise Noted)

Symbol	Parameter		Rating	Units	
V _{DS}	Drain-Source Voltage	•	60	\\	
V _{GS}	Gate-Source Voltage		±20	V	
I _S	Diode Continuous Forward Current	T _C =25°C	155		
	Continuous Dunin Comment	T _C =25°C	155	۸	
I _D	Continuous Drain Current	T _C =100°C	117	Α	
I _{DM} ²	Pulse Drain Current	T _C =25°C	465		
D	Marianum Davier Dissipation	T _C =25°C	250	14/	
P_{D}	Maximum Power Dissipation	T _C =100°C	125	W	
R _{θJA} ⁴	Thermal Resistance-Junction to Ambient	Steady State	62.5	9004	
$R_{ heta JC}$	Thermal Resistance-Junction to Case		0.6	°C/W	
I _{AS} ³	Avalanche Current, Single pulse	L=0.5mH	48	Α	
E _{AS} ³	Avalanche Energy, Single pulse	L=0.5mH	576	mJ	
T _{STG}	Storage Temperature Range		-55 to 150	°0	
TJ	Maximum Junction Temperature		150	°C	



Electrical Characteristics (T_A=25°C, Unless Otherwise Noted)

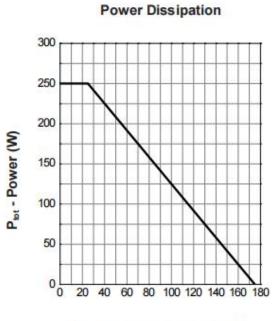
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250μA	60			V
	Zana Oata Valtana Basin Ourrant	V _{DS} =48V , V _{GS} =0V			1.0	
I _{DSS}	Zero Gate Voltage Drain Current	T _J =85°C			30	μA
V _{GS(th)}	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_{DS}=250\mu A$	2.0	3.0	4.0	V
I _{GSS}	Gate Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA
R _{DS(ON)} ⁵	Drain-Source On-state Resistance	V_{GS} =10V , I_D =60A		2.4	2.6	mΩ
Diode Chara	cteristics					
V _{SD} ⁵	Diode Forward Voltage	I _{SD} =60A , V _{GS} =0V		0.8	1.3	V
t _{rr}	Reverse Recovery Time	1 -COA d: /dt-400A/		71		ns
Q _{rr}	Reverse Recovery Charge	- I _{DS} =60A , di _{SD} /dt=100A/μs		103		nC
Dynamic Cha	aracteristics ⁶					
R_g	Gate Resistance	V _{GS} =0V , V _{DS} =0V , <i>f</i> =1.0MHz		1.8		Ω
C _{iss}	Input Capacitance	V _{GS} =0V , V _{DS} =30V ,		3907	5350	pF
C _{oss}	Output Capacitance			1154		
C _{rss}	Reverse Transfer Capacitance	Frequency=1.0MHz		30		
T _{d(on)}	Turn-on Delay Time			31		
T _r	Turn-on Rise Time	V_{DD} =30V , R_L =30 Ω , I_{DS} =1A ,		18		ns
T _{d(off)}	Turn-off Delay Time	V_{GEN} =10V , R_{G} =6 Ω		100		
T _f	Turn-off Fall Time			195		
Gate Charge	Characteristics ⁶					
Qg	Total Gate Charge			93		
Q _{gs}	Gate-Source Charge	V _{DS} =30V , V _{GS} =10V , I _{DS} =60A		24		nC
Q_gd	Gate-Drain Charge			11.6		

Note:

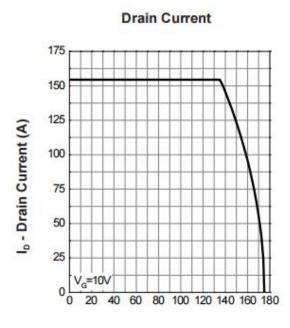
- 1. Calculated continuous current based on maximum allowable junction temperature. Bonding wire limitation current is 8A.
- 2. Pulse width limited by max. junction temperature.
- 3. UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature T_J =25°C).
- 4. Surface Mounted on 1in² pad area.
- 5. Pulse test ; pulse width≤300µs, duty cycle≤2%.
- 6. Guaranteed by design, not subject to production testing.



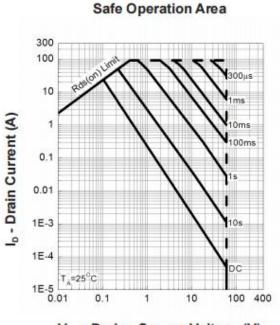
Typical Characteristics

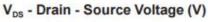


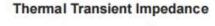
T_c - Case Temperature (°C)

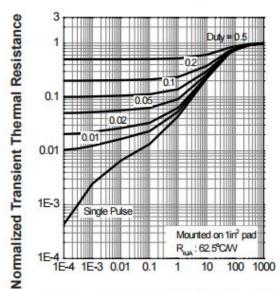


T_c - Case Temperature (°C)







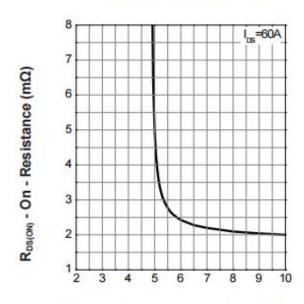


Square Wave Pulse Duration (sec)



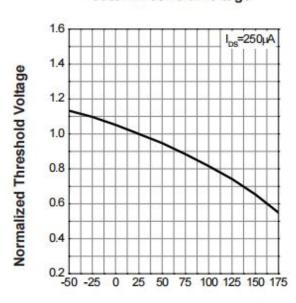
Typical Characteristics (Cont.)

Gate-Source On Resistance



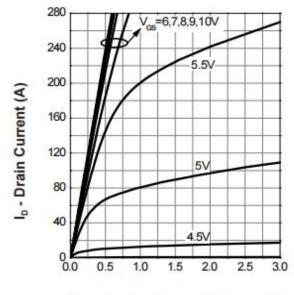
V_{GS} - Gate - Source Voltage (V)

Gate Threshold Voltage



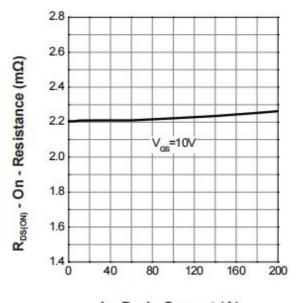
T_i - Junction Temperature (°C)

Output Characteristics



V_{DS} - Drain - Source Voltage (V)

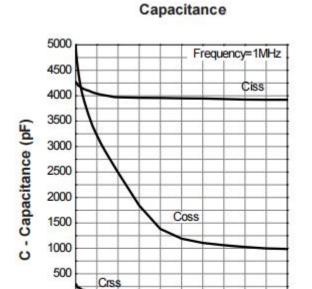
Drain-Source On Resistance



Ip - Drain Current (A)



Typical Characteristics (Cont.)



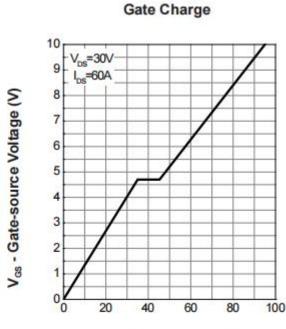
V_{DS} - Drain-Source Voltage (V)

30

40

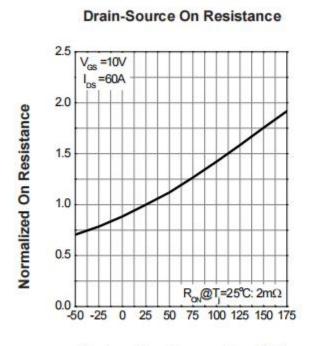
20

10

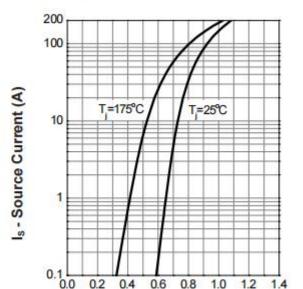


Q_G - Gate Charge (nC)

Source-Drain Diode Forward



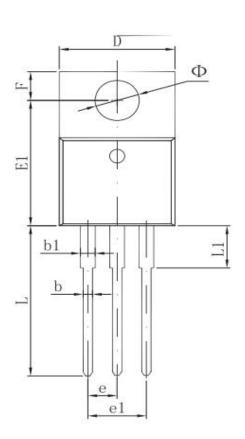
T_i - Junction Temperature (°C)

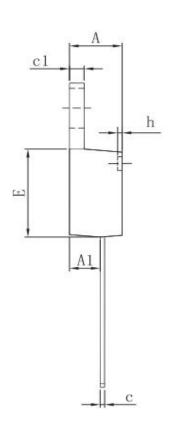


V_{sp} - Source - Drain Voltage (V)



Packaging information





Symbol	Dimensions In Millimeters		Dimension	s In Inches
	Min	Max	Min	Max
A	4.470	4.670	0.176	0.184
A1	2.520	2.820	0.099	0.111
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
С	0.310	0.530	0.012	0.021
c1	1.170	1.370	0.046	0.054
D	10.010	10.310	0.394	0.406
Е	8.500	8.900	0.335	0.350
E1	12.060	12.460	0.475	0.491
е	2.540 TYP		0. 100 TYP	
e1	4.980	5. 180	0.196	0.204
F	2.590	2.890	0.102	0.114
h	0.000	0.300	0.000	0.012
L	13.400	13.800	0.528	0. 543
L1	3.560	3.960	0.140	0.156
Φ	3.735	3.935	0.147	0.155



N-Channel MOSFET

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